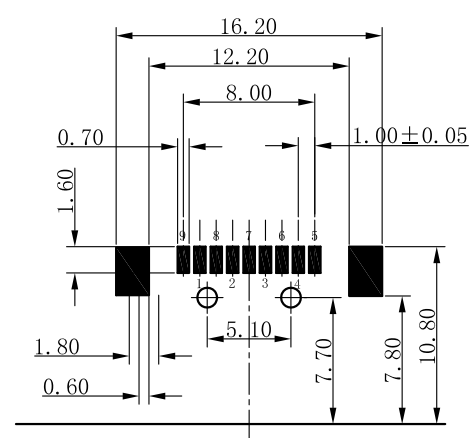
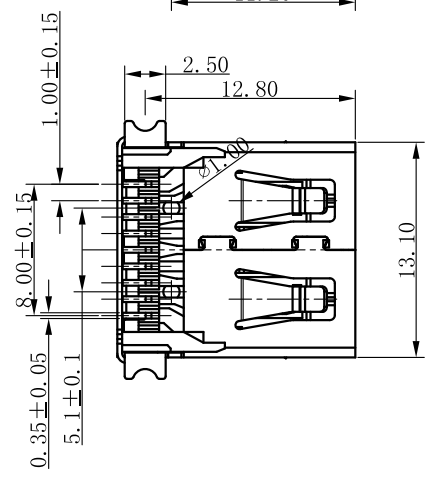
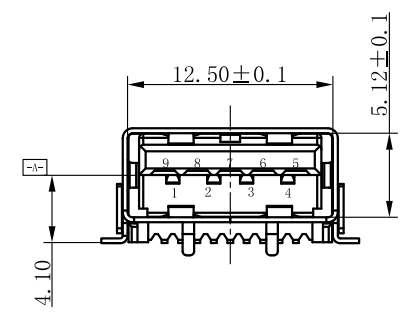
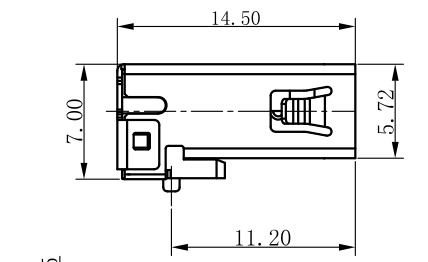
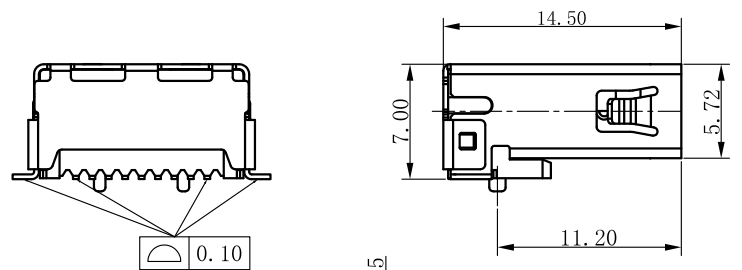
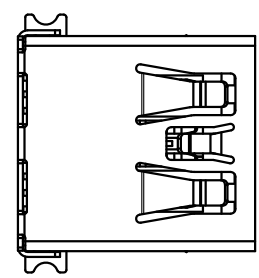


REV.	ECN.NO.	APPD.
A	/	/



PCB EDGE  
RECOMMENDED PCB LAYOUT



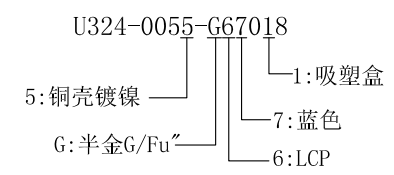
Remark:

1.MATERIAL:

- 1.1 Housing:thermoplastic plastics.
- 1.2 terminals:Copper Alloy
- 1.3 Front Shell:Copper Alloy/SPCC.  
Middle Shell:SPCC

2.characteristics:

- 2.1 Rating Voltage : 30V AC.
- 2.2 Rating Current:PIN1&PIN4(Vbus&Correponding ground PIN)  
1.8A MAX Other PINS 0.25A min.
- 2.3 Contact Resistance:PIN1&PIN4:30 mΩ MAX. Other PINS: 50 mΩ
- 2.4 Insulation Resistance:100 MΩ MIN.
- 2.5 Withstanding Voltage:AC 100V between adjacent contacts
- 2.6 Mating force: 3.57Kgf MAX(35N MAX)
- 2.7 Extraction force:1Kgf Min(9.8N Min)
- 2.8 Life test:1500Cycles MIN.
- 2.9 Temperature Range: -30℃~+80℃.



TOLERANCE UNLESS OTHERWISE SPECIFIED		<b>FLW</b> 深圳市华联威电子科技有限公司 HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.				
.XXX ±0.10	.XX ±0.20	.X ±3°				
.X ±0.30	.XX ±2°					
APPROVED		PART NAME:	USB 3.0 AF 全贴片 无卷边 铜壳			
CHECKED		PART No:	U324-0055-G67018	C		
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE	SHEET	REV.
DATE	2023.04.06		mm	1:1	10F1	A